

## 6500/1 ONE-CHIP MICROCOMPUTER

### INTRODUCTION

The MOS Technology 6500/1 is a complete, high-performance 8-bit NMOS microcomputer on a single chip, and is totally upward/downward software compatible with all members of the 6500 family.

The 6500/1 consists of a 6502 CPU, an internal clock oscillator, 2048 bytes of Read Only Memory (ROM), 64 bytes of Random Access Memory (RAM) and flexible interface circuitry. The interface circuitry includes a 16-bit programmable counter/latch with four operating modes, 32 bidirectional input/output lines (including two edge-sensitive lines), five interrupts and a counter I/O line.

### PRODUCT SUPPORT

To allow prototype circuit development, Mos Technology offers a PROM compatible 64-pin Emulator device. This device provides all 6500/1 interface lines plus routing the address bus, data bus, and associated control lines off the chip to be connected to external memory.

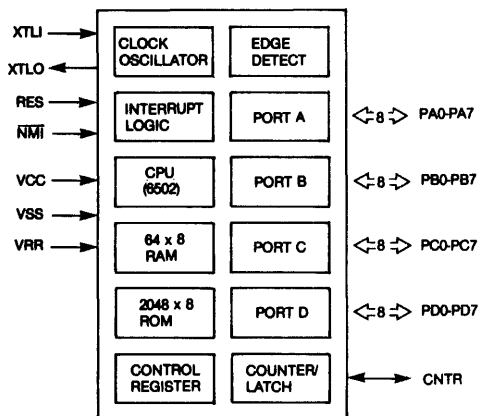
#### ORDERING INFORMATION

Order Number	Package Type	Frequency Option	Temperature Range
MPS6500/1	Plastic	1 MHz	0°C to 70°C
MCS6500/1	Ceramic	1 MHz	0°C to 70°C
MPS6500/1A	Plastic	2 MHz	0°C to 70°C
MCS6500/1A	Ceramic	2 MHz	0°C to 70°C
MCS6500/1E	Emulator Device 1MHz		
MCS6500/1EA	Emulator Device 2MHz		

**Note:** The RC frequency option is available only in the 1 MHz 6500/1.

### FEATURES

- 6502 CPU
  - Software upward/downward compatibility
  - Decimal or binary arithmetic modes
  - 13 addressing modes
  - True direct and indirect indexing
  - Memory addressable I/O
- 2048 x 8 mask programmable ROM
- 64 x 8 static RAM
- 32 bi-directional TTL compatible I/O lines (4 ports)
- 1 bi-directional TTL compatible counter I/O line
- 16-bit programmable counter/latch with four modes
  - Interval Timer
  - Event Counter
  - Pulse Generator
  - Pulse Width Measurement
- Five Interrupts
  - Reset
  - Non-maskable
  - Two external edge sensitive
  - Counter
- 1 of 3 frequency references
  - Crystal
  - Clock
  - RC (resistor only)
- 4 MHz max crystal or clock external frequency
- 2 MHz or 1 MHz internal clock
- 1  $\mu$ s minimum instruction execution
- N-channel, silicon gate, depletion load technology
- Single +5V power supply
- 500 mW operating power
- Separate power pin for RAM
- 40 pin DIP
- 64 pin PROM compatible Emulator device



Interface Diagram

## FUNCTIONAL DESCRIPTION

### CENTRAL PROCESSING UNIT (CPU)

#### Clock Oscillator

The Clock Oscillator provides the basic timing signals used by the 6500/1 CPU. The reference frequency is provided by an external source, and can be from a crystal, clock or RC network input. The RC network mode is a mask option. The external frequency can vary from 200 kHz to 4 MHz. The internal Phase 2 (Ø2) frequency is one-half the external reference frequency. A 4.7K ohm resistor will provide nominal 2 MHz oscillation and 1 MHz internal operation in the RC mask option ( $\pm 35\%$ ).

#### Timing Control

The Timing Control Logic keeps track of the specific instruction cycle being executed. Each data transfer which takes place between the registers is caused by decoding the contents of both the Instruction Register and Timing Control Logic.

#### Program Counter

The 16-bit Program Counter provides the addresses which step the CPU through sequential instructions in a program. The Program Counter is incremented each time an instruction or data is fetched from memory.

#### Instruction Register and Decode

Instructions fetched from memory are gated onto the Internal Data Bus. These instructions are latched into the Instruction Register then decoded, along with timing and interrupt signals, to generate control signals for the various registers.

#### Arithmetic and Logic Unit (ALU)

All arithmetic and logic operations take place in the ALU, including incrementing and decrementing internal registers (except the Program Counter).

#### Accumulator

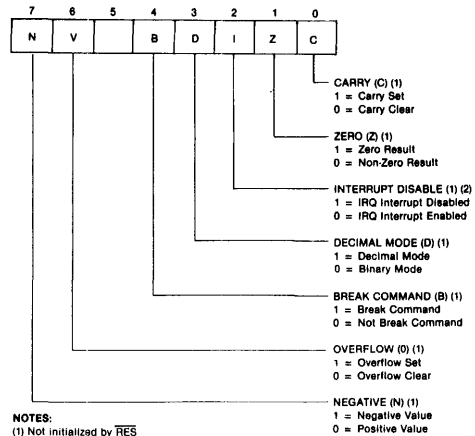
The accumulator is a general purpose 8-bit register that stores the results of most arithmetic and logic operations. In addition, the accumulator usually contains one of the two data words used in these operations.

#### Index Registers

There are two 8-bit index registers, X and Y. These registers can be used for general purpose storage, or as a displacement to modify the base address and thus obtain a new effective address. Pre- or post-indexing of indirect addresses is possible.

#### Stack Pointer

The Stack Pointer is an 8-bit register. It is automatically incremented and decremented under control of the CPU to perform stack manipulation under direction of either the program or interrupts NMI and IRQ. The stack allows simple implementation of nested subroutines and multiple level interrupts.



### Processor Status Register

#### Processor Status Register

The 8-bit Processor Status Register contains seven status flags. Some of the flags are controlled by the program, others may be controlled both by the program and the CPU. The 6500 instruction set contains a number of conditional branch instructions which are designed to allow testing of these flags.

#### Interrupt Logic

Interrupt logic controls the sequencing of three interrupts; RES, NMI and IRQ. IRQ is generated by any one of three conditions: Counter Overflow, PA0 Positive Edge Detected, and PA1 Negative Edge Detected.

### MEMORY

#### 2048 x 8 ROM

The 2048 byte Read-Only Memory (ROM) contains the program instructions and other fixed constants. These program instructions and constants are mask programmed into the ROM during fabrication of the 6500/1 device. The 6500/1 ROM is memory mapped from 800 to FFF.

#### 64 x 8 RAM

The 64 byte Random Access Memory (RAM) is used for read/write memory during system operation, and contains the stack. This RAM is completely static in operation and requires no clock or dynamic refresh. A standby power pin, VRR, allows RAM memory to be maintained on 10% of the operating power in the event that VCC power is lost.

In order to take advantage of efficient zero page addressing capabilities, the RAM is assigned memory addresses 0 to 03F.

## INPUT/OUTPUT

### Bidirectional I/O Ports

The 6500/1 provides four 8-bit input/output ports (PA, PB, PC, and PD). Associated with the I/O ports are four 8-bit registers located on page zero. See the system memory map for specific addresses. Each I/O line is individually selectable as an input or an output without line grouping or port association restrictions.

An internal active transistor drives each I/O line to the low state. An internal passive resistance pulls the I/O lines to the high state, eliminating the need for external pull-up resistors.

An option is available to delete the internal pull-up resistance on 8-bit port groups or on the CNTR line at mask time. This option is employed to permanently assign an 8-bit port group to input functions, to interface with CMOS drivers, or to interface with external pull-up devices.

### Inputs

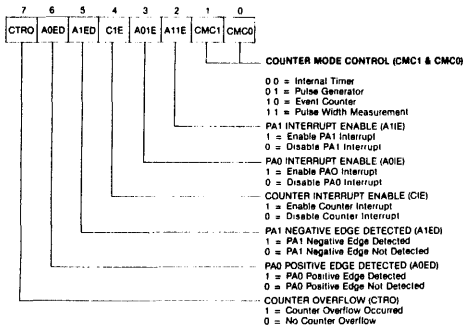
Inputs are enabled by setting the appropriate bit of the I/O port to the high state (Logic 1). A low input signal causes a logic 0 to be read. A high input signal causes a logic 1 to be read. RES loads Logic 1 into the I/O ports, thereby initializing all I/O lines as inputs.

### Outputs

Outputs are set by loading the desired bit pattern into the corresponding I/O ports. A Logic 1 selects a high output; a Logic 0 selects a low output.

## CONTROL REGISTER

The Control Register (CR) controls four Counter operating modes and three maskable interrupts. It also reports the status of three interrupt conditions. There are five control bits and three status bits. The control bits are set to Logic 1 or cleared to Logic 0 by writing the desired state into the respective bit positions. The Control Register is cleared to Logic 0 by the occurrence of RES.



Control Register

## EDGE DETECT CAPABILITY

There is an asynchronous edge detect capability on two of the Port A I/O lines. This capability exists in addition to and independently from the normal Port A I/O functions. The maximum rate at which an edge can be detected is one-half the  $\varnothing$ 2 clock rate. The edge detect logic is continuously active. Each edge detect signal is associated with a maskable interrupt.

### PA0 Positive Edge Detection

A positive (rising) edge is detectable on PA0. When this edge is detected, the PA0 Positive Edge Detected bit—Bit 6 in the Control Register—is set to Logic 1. When both this bit and the PA0 Interrupt Enable Bit—Bit 3 of the Control Register—are set to Logic 1, an IRQ interrupt request is generated. The PA0 Positive Edge Detected bit is cleared by writing to address 089.

### PA1 Negative Edge Detection

A negative (falling) edge is detectable on PA1. When this edge is detected, the PA1 Negative Edge Detected bit—Bit 5 of the Control Register—is set to Logic 1. When both this bit and the PA1 Interrupt Enable bit—Bit 2 of the Control Register—are set to Logic 1, an IRQ interrupt request is generated. The PA1 Negative Edge Detected bit is cleared by writing to address 08A.

## COUNTER/LATCH

The Counter/Latch consists of a 16-bit decrementing Counter and a 16-bit Latch. The Counter is comprised of two 8-bit registers. Address 086 contains the Upper Count (UC) and address 087 contains the Lower Count (LC). The Counter counts either  $\varnothing$ 2 clock periods or occurrences of an external event, depending on the selected counter mode. The UC and LC can be read at any time without affecting counter operation.

The Latch contains the Counter preset value. The Latch consists of two 8-bit registers. Address 084 contains the Upper Latch (UL) and address 085 contains the lower latch (LL). The 16-bit Latch can hold a count from 0 to 65,535. The Latch can be accessed as two write-only memory locations.

The Latch registers can be loaded at any time by storing into UL and LL. The UL can also be loaded by writing into address 088.

The Counter can be preset at any time by writing to address 088. Presetting the Counter in this manner causes the contents of the accumulator to be stored into the UL before the 16-bit value in the Latch (UL and LL) is transferred in the Counter (UC and LC).

The Counter is preset to the Latch value when the Counter overflows. When the counter decrements from 0000, Counter overflow occurs causing the next counter value to be the Latch value, not FFFF.

When the Counter overflows, Counter Overflow bit—Bit 7 of the Control Register—is set to Logic 1. When both this bit and the Counter Interrupt Enable bit—Bit 4 of the Control Register—are set, an IRQ interrupt request is generated. The Counter Overflow bit in the Control Register can be examined in an IRQ interrupt service routine to determine that the IRQ was generated by Counter overflow.

The Counter Overflow bit is cleared when the LC is read or Counter preset is performed by writing into address 088.

## COUNTER MODES

The Counter operates in any of four modes. These modes are selected by the Counter Mode Control bits in the Control Register.

Mode	CMC 1	CMC 0
Interval Timer	0	0
Pulse Generator	0	1
Event Counter	1	0
Pulse Width Measurement	1	1

The Interval Timer, Pulse Generator, and Pulse Width Measurement Modes are  $\varnothing 2$  clock counter modes. The Event Counter Mode counts the occurrences of an external event on the CNTR line.

### Interval Timer (Mode 0)

In this mode the Counter is free running and decrements at the  $\varnothing 2$  clock rate. Counter overflow sets the Control Register status bit and causes the Counter to be preset to the Latch value.

The CNTR line is held in the high state.

### Pulse Generator (Mode 1)

In this mode the Counter is free running and decrements at the  $\varnothing 2$  clock rate. Counter overflow sets the Control Register status bit and causes the Counter to be preset to the Latch value.

The CNTR line toggles from one state to the other when Counter overflow occurs. Writing to address 088 will also toggle the CNTR line.

A symmetric or asymmetric output waveform can be generated on the CNTR line in this mode. A one-shot waveform can easily be generated by changing from Mode 1 to Mode 0 after only one occurrence of the output toggle condition.

### Event Counter (Mode 2)

In this mode the CNTR line is used as an event input line. The Counter decrements each time a rising edge is detected on CNTR. The maximum rate at which this edge can be detected is one-half the  $\varnothing 2$  clock rate. Counter overflow sets the Control Register status bit and causes the Counter to be preset to the Latch value.

### Pulse Width Measurement (Mode 3)

This mode allows the accurate measurement of the duration of a low state on the CNTR line. The Counter decrements at the  $\varnothing 2$  clock rate as long as the CNTR line is held in the low state. The Counter is stopped when CNTR is in the high state. If the CNTR pin is left disconnected, this mode may be selected to stop the Counter since the internal pull-up device will cause the CNTR input to be in the high state.

## RESET CONSIDERATIONS

The occurrence of  $\overline{RES}$  going from low to high causes initialization of various conditions in the 6500/1. All of the I/O ports (PA, PB, PC, and PD) and

CNTR are forced to the high (Logic 1) state. All bits of the Control Register are reset to Logic 0, causing the Interval Timer Mode (Mode 0) to be selected and all interrupt enabled bits to be cleared. Neither the Latch nor the Counter registers are initialized by  $\overline{RES}$ . The Interrupt Disable bit in the CPU Processor Status Register is set and the program starts execution at the address contained in the Reset Vector location.

## TEST LOGIC

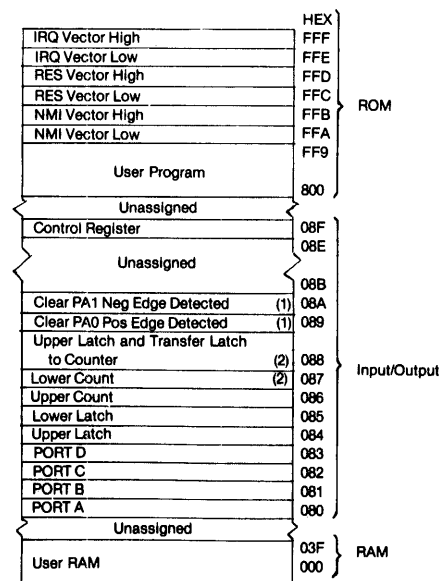
Special test logic provides a method for thoroughly testing the 6500/1. Applying a +10V signal to the  $\overline{RES}$  line places the 6500/1 in the test mode. While in this mode, all memory fetches are made from Port PC. External test equipment can use this feature to test internal CPU logic and I/O. A program can be loaded into RAM allowing the contents of the instruction ROM to be dumped to any port for external verification.

All 6500/1 microcomputers are tested by MOS Technology using this feature.

## MEMORY ADDRESSABLE I/O

The I/O ports, registers, and commands are treated as memory and are assigned specific addresses. See the system memory map for the addresses. This I/O technique allows the full set of CPU instructions to be used in the generation and sampling of I/O commands and data. When an instruction is executed with an I/O address and appropriate R/W state, the corresponding I/O function is performed.

## SYSTEM MEMORY MAP



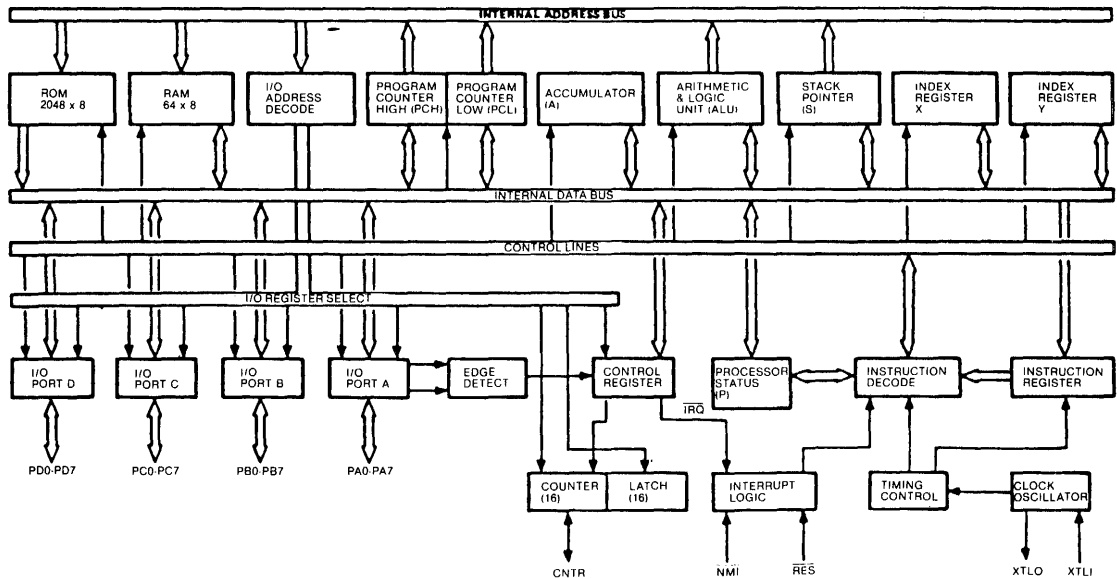
### Notes:

- (1) I/O command only; i.e., no stored data.
- (2) Clears Counter Overflow—Bit 7 in Control Register.

## INSTRUCTION SET—ALPHABETIC SEQUENCE

ADC	Add Memory to Accumulator with Carry	LDA	Load Accumulator with Memory
AND	"AND" Memory with Accumulator	LDX	Load Index X with Memory
ASL	Shift Left One Bit (Memory or Accumulator)	LDY	Load Index Y with Memory
BCC	Branch on Carry Clear	LSR	Shift One Bit Right (Memory or Accumulator)
BCS	Branch on Carry Set	NOP	No operation
BEO	Branch on Result Zero	ORA	"OR" Memory with Accumulator
BIT	Test Bits in Memory with Accumulator	PHA	Push Accumulator on Stack
BMI	Branch on Result Minus	PHP	Push Processor Status on Stack
BNE	Branch on Result not Zero	PLA	Pull Accumulator from Stack
BPL	Branch on Result Plus	PLP	Pull Processor Status from Stack
BRK	Force Break	ROL	Rotate One Bit Left (Memory or Accumulator)
BVC	Branch on Overflow Clear	ROR	Rotate One Bit Right (Memory or Accumulator)
BVS	Branch on Overflow Set	RTI	Return from Interrupt
CLC	Clear Carry Flag	RTS	Return from Subroutine
CLD	Clear Decimal Mode	SBC	Subtract Memory from Accumulator with Borrow
CLI	Clear Interrupt Disable Bit	SEC	Set Carry Flag
CLV	Clear Overflow Flag	SED	Set Decimal Mode
CMP	Compare Memory and Accumulator	SEI	Set Interrupt Disable Status
CPX	Compare Memory and Index X	STA	Store Accumulator in Memory
CPY	Compare Memory and Index Y	STX	Store Index X in Memory
DEC	Decrement Memory by One	STY	Store Index Y in Memory
DEX	Decrement Index X by One	TAX	Transfer Accumulator to Index X
DEY	Decrement Index Y by One	TAY	Transfer Accumulator to Index Y
EOR	"Exclusive-or" Memory with Accumulator	TSX	Transfer Stack Pointer to Index X
INC	Increment Memory by One	TXA	Transfer Index X to Accumulator
INX	Increment Index X by One	TXS	Transfer Index X to Stack Register
INY	Increment Index Y by One	TYA	Transfer Index Y to Accumulator
JMP	Jump to New Location		
JSR	Jump to New Location Saving Return Address		

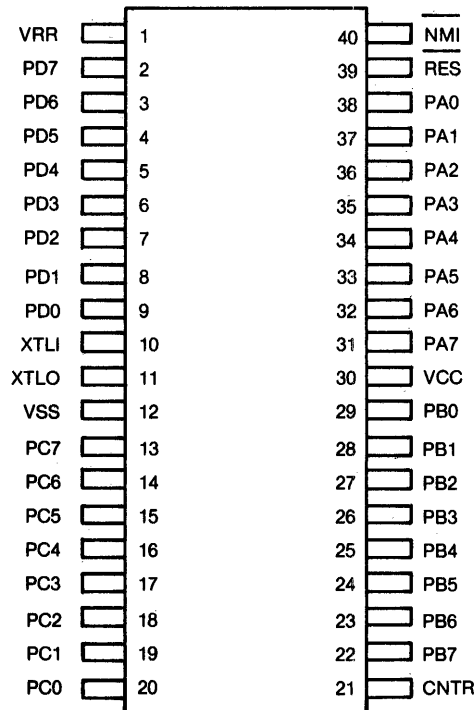
6500/1 Block Diagram



**SIGNAL DESCRIPTIONS**

SIGNAL NAME	PIN NO.	DESCRIPTION
VCC	30	Main power supply +5V
VRR	1	Separate power pin for RAM. In the event that VCC power is lost, this power retains RAM data.
VSS	12	Signal ground
XTLI	10	Crystal, clock or RC network input for internal clock oscillator.
XTLO	11	Crystal or RC network output from internal clock oscillator.
RES	39	The Reset input is used to initialize the 6500/1. This signal must not transition from low to high for at least eight cycles after VCC reaches operating range and the internal oscillator has stabilized. +10V input enables the test mode.

SIGNAL NAME	PIN NO.	DESCRIPTION
NMI	40	A negative going edge on the Non-Maskable Interrupt signal requests that a non-maskable interrupt be generated within the CPU.
PA0-PA7	38-31	Four 8 bit ports used for either input/output. Each line consists of an active transistor to VSS and a passive pull-up to +5V. The two lower bits of the PA port (PA0 and PA1) also serve as edge detect inputs with maskable interrupts.
PB0-PB7	29-22	
PC0-PC7	20-13	
PD0-PD7	9-2	
CNTR	21	This line is used as a Counter input/output line. CNTR is an input in the Event Counter and Pulse Width Measurement modes and is an output in the Interval Timer and Pulse Generator modes.


**Pin Configuration**

**ADDRESSING MODES**

**ACCUMULATOR ADDRESSING**—This form of addressing is represented with a one byte instruction, implying an operation on the accumulator.

**IMMEDIATE ADDRESSING**—In immediate addressing, the operand is contained in the second byte of the instruction, with no further memory addressing required.

**ABSOLUTE ADDRESSING**—In absolute addressing, the second byte of the instruction specifies the eight low order bits of the effective address while the third byte specifies the eight high order bits.

**ZERO PAGE ADDRESSING**—The zero page instructions allow for shorter code and execution times by only fetching the second byte of the instruction and assuming a zero high address byte. Careful use of the zero page can result in significant increase in code efficiency.

**INDEXED ZERO PAGE ADDRESSING**—(X, Y Indexing)—This form of addressing is used in conjunction with the index register and is referred to as "Zero Page, X" or "Zero Page, Y." The effective address is calculated by adding the second byte to the contents of the index register. Since this is a form of "Zero Page" addressing, the content of the second byte references a location in page zero. Additionally due to the "Zero Page" addressing nature of this mode, no carry is added to the high order 8 bits of memory and crossing of page boundaries does not occur.

**INDEXED ABSOLUTE ADDRESSING**—(X, Y Indexing)—This form of addressing is used in conjunction with X and Y index register and is referred to as "Absolute, X", and "Absolute, Y." The effective address is formed by adding the contents of X or Y to the address contained in the second and third bytes of the instruction. This mode allows the index register to contain the index or count value and the instruction to contain the base address. This type of indexing allows any location referencing and the index to modify multiple fields resulting in reduced coding and execution time.

**IMPLIED ADDRESSING**—In the implied addressing mode, the address containing the operand is implicitly stated in the operation code of the instruction.

**RELATIVE ADDRESSING**—Relative addressing is used only with branch instructions and establishes a destination for the conditional branch.

The second byte of the instruction becomes the operand which is an "Offset" added to the contents of the lower eight bits of the program counter when the counter is set at the next instruction. The range of the offset is - 128 to + 127 bytes from the next instruction.

**INDEXED INDIRECT ADDRESSING**—In indexed indirect addressing (referred to as [Indirect, X]), the second byte of the instruction is added to the contents of the X index register, discarding the carry. The result of this addition points to a memory location on page zero whose contents is the low order eight bits of the effective address. The next memory location in page zero contains the high order eight bits of the effective address. Both memory locations specifying the high and low order bytes of the effective address must be in page zero.

**INDIRECT INDEXED ADDRESSING**—In indirect indexed addressing (referred to as [Indirect, Y]), the second byte of the instruction points to a memory location in page zero. The contents of this memory location are added to the contents of the Y index register, the result being the low order eight bits of the effective address. The carry from this addition is added to the contents of the next page zero memory location, the result being the high order eight bits of the effective address.

**ABSOLUTE INDIRECT**—The second byte of the instruction contains the low order eight bits of a memory location. The high order eight bits of this memory location are contained in the third byte of the instruction. The contents of the fully specified memory location are the low order byte of the effective address. The next memory location contains the high order byte of the effective address which is loaded into the sixteen bits of the program counter.





**SPECIFICATIONS**
**Maximum Ratings**

Rating	Symbol	Value	Unit
Supply Voltage	$V_{CC}$	-0.3 to +7.0	Vdc
Input Voltage	$V_{in}$	-0.3 to +7.0	Vdc
Operating Temperature Range	$T_A$	0 to +70	°C
Storage Temperature Range	$T_{stg}$	-55 to +150	°C

This device contains circuitry to protect the inputs against damage due to high static voltages, however, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to this circuit.

**Static D.C. Characteristics ( $V_{CC} = 5V \pm 5\%$ ,  $T_A = 0^\circ - 70^\circ C$ )**

Characteristic	Symbol	Min	Typ	Max	Unit
Power Dissipation (Outputs High)	$P_D$	—	500	—	mW
RAM Standby Voltage (Retention Mode)	$V_{RR}$	3.5	—	$V_{CC}$	Vdc
RAM Standby Current (Retention Mode)	$I_{RR}$	—	10	—	mAdc
Input High Voltage (Normal Operating Levels)	$V_{IH}$	+2.0	—	$V_{CC}$	Vdc
Input Low Voltage (Normal Operating Levels)	$V_{IL}$	-0.3	—	+0.8	Vdc
Input Leakage Current $V_{in} = 0$ to 5.0 Vdc	$I_{IN}$	—	$\pm 1.0$	$\pm 2.5$	$\mu$ Adc
RES, NMI			$\pm 1.0$	—	$\mu$ Adc
Input High Voltage (XTLI)	$V_{IHXT}$	+4.0	—	$V_{CC}$	Vdc
Input Low Voltage (XTLI)	$V_{ILXT}$	-0.3	—	+0.8	Vdc
Input Low Current ( $V_{IL} = 0.4$ Vdc)	$I_{IL}$	—	-1.0	-1.6	mAdc
Output High Voltage ( $V_{CC} = \text{min}$ , $I_{Load} = -100 \mu\text{Adc}$ )	$V_{OH}$	-2.4	—	—	Vdc
Output High Voltage ( $V_{CC} = \text{min}$ )	$V_{CMOS}$	$V_{CC} - 30\%$	—	—	Vdc
Output Low Voltage ( $V_{CC} = \text{min}$ , $I_{Load} = 1.6$ mAdc)	$V_{OL}$	—	—	+0.4	Vdc
Output High Current (Sourcing) ( $V_{OH} = 2.4$ Vdc)	$I_{OH}$	-100	—	—	$\mu$ Adc
Output Low Current (Sinking) ( $V_{OL} = 0.4$ Vdc)	$I_{OL}$	1.6	—	—	mAdc
Input Capacitance ( $V_{in} = 0$ , $T_A = 25^\circ C$ , $f = 1.0$ MHz) PA, PB, PC, PD, CNTR	$C_{in}$	—	—	10	pF
XTLI, XTLO				50	pF
Output Capacitance ( $V_{in} = 0$ , $T_A = 25^\circ C$ , $f = 1.0$ MHz)	$C_{out}$	—	—	10	pF
I/O Port Resistance PA0-PA7, PB0-PB7, PC0-PC7, PD0-PD7, CNTR	$R_L$	3.0	6.0	11.5	K $\Omega$

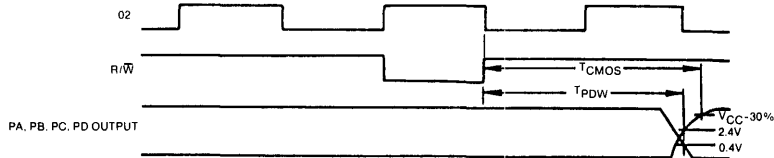
NOTE: Negative sign indicates outward current flow, positive indicates inward flow.

### AC Characteristics ( $V_{CC} = 5V \pm 5\%$ , $T_A = 0^\circ$ to $70^\circ C$ )

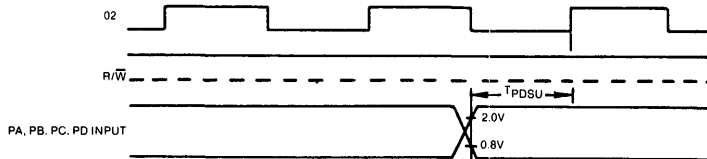
Parameter	Symbol	1 MHz		2 MHz		Unit
		Min	Max	Min	Max	
XTLI Input Clock Cycle Time	$T_{cyc}$	0.500	5.0	0.250	5.0	$\mu sec$
Internal Write to Peripheral Data Valid (TTL)	$T_{PDW}$	1.0	—	0.5	—	$\mu sec$
Internal Write to Peripheral Data Valid (CMOS)	$T_{CMOS}$	2.0	—	1.0	—	$\mu sec$
Peripheral Data Setup Time	$T_{PDSU}$	400	—	200	—	nsec
Count and Edge Detect Pulse Width	$T_{PW}$	1.0	—	0.5	—	$\mu sec$

### TIMING CHARACTERISTICS

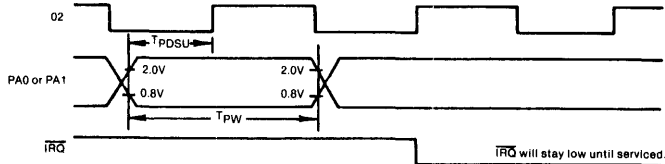
#### I/O PORT OUTPUT TIMING



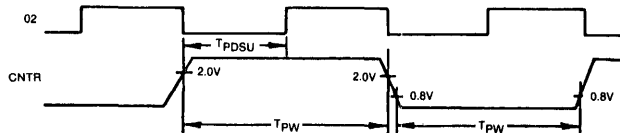
#### I/O PORT INPUT TIMING



#### PA0 AND PA1 EDGE DETECT TIMING



#### EVENT COUNTER TIMING



**PROGRAMMING INSTRUCTIONS FOR MOS TECHNOLOGY 6500/1**

MOS Technology utilizes computer aided techniques to manufacture and test custom bit patterns. New custom bit data and address information is supplied on standard 80 column computer cards, 1 inch wide paper tape, or standard 1/4 inch wide audio tape cassette, or 2708/2716 EPROMS. ROM Data will also be accepted in other formats. Consult MOS Technology for details.

**MOS TECHNOLOGY (6500) CARD FORMAT**

All addresses and related bit patterns must be completely defined. Each deck of cards consists of: 1) Four Title Cards, 2) Address and Memory Data Records.

Positive logic is generally used on all input cards: A logic "1" is the most positive or high level (True), and logic "0" is the most negative or low level (False). This includes chip select specifications as well as bit patterns.

**TITLE CARDS**

	<u>COLUMN</u>	<u>INFORMATION</u>
FIRST CARD	1-4	MOS PART NUMBER (6500/1)
	5-80	BLANK (FOR MOS TECHNOLOGY USE)
SECOND CARD	1-20	CUSTOMER NAME
	21-40	CUSTOMER PART NUMBER
	41-60	CUSTOMER TECHNICAL CONTACT (PERSON)
	61-80	CUSTOMER PHONE NUMBER
THIRD CARD	1-20	DATA FORMAT (PUNCH "MOS")
	21-40	LOGIC FORMAT (PUNCH "POSITIVE" OR "NEGATIVE")
	41-60	VERIFICATION CODE (PUNCH "HOLD" IF CUSTOMER APPROVAL REQ., PUNCH "OKAY" IF FINAL APPROVAL NOT REQ.)
	61-80	BLANK (FOR MOS TECHNOLOGY USE)
FOURTH CARD	1-6	PULLUP SELECT CARD (PUNCH "PULLUP")
	7	PULLUP OPTION FOR I/O PORT A;1 = PULLUP
	8	PULLUP OPTION FOR I/O PORT B;1 = PULLUP
	9	PULLUP OPTION FOR I/O PORT C;1 = PULLUP
	10	PULLUP OPTION FOR I/O PORT D;1 = PULLUP

A set of four (4) Title Cards should accompany each data deck. These cards provide our computer programs additional information necessary to accurately produce the ROM Data. These four Title Cards must contain the above information.

**MOS CARD DECK FORMAT**

Output data is punched on standard 80 column cards in ASCII Hollerith Code. Each byte of data to be stored is converted to two half bytes. The half bytes (whose possible values are 0 to F<sub>HEX</sub>) are translated into their ASCII equivalents and punched onto cards. Each record contains record length, memory address, and checksum information in addition to data. A column by column description of a data record follows.

- COLUMN ONE** — **Record Mark.** Signals start of record. ASCII character " ; " (HEX 3B)
- COL. 2-3** — **Record Length.** Two ASCII characters representing a HEX number in the range 0 to 18<sub>HEX</sub> (0 to 24). This is the count of actual data bytes in the record. A record length of 0 indicates end of file.
- COL. 4-7** — **Load Address.** Four ASCII characters. The starting address high and starting address low are the left and right bytes respectively. The first data byte is stored in the memory location pointed to by the load address, succeeding data bytes are loaded into ascending address.
- COL. 8-n** — **Data.** Each 8 bit memory word is represented by two ASCII characters (0 to 9, A to F) to represent a hexadecimal number (0 to 255).  

$$\left\{ n = 8 + 2^{\left( \frac{\text{RECORD}}{\text{LENGTH}} \right) - 1} \right\}$$
- COL. n+1-n+5** — **Checksum.** The sum of all 8 bit bytes in the record since the record mark ( ; ) in four ASCII characters (HEX).
- REMAINING COLUMNS** — Not Used. Leave blank or use for comment or labels.
- SPECIAL LAST CARD** — As mentioned above, a record length of zero ("0") indicates an end of file. Following the record length on this terminal record should be a four character ASCII (HEX) count of all data records in deck. Following this is the usual checksum for this record.

See the example under heading "MOS PAPER TAPE FORMAT."  
 A set of four title cards should accompany each data deck.

**MOS PAPER TAPE FORMAT**

The paper tape which should be used is 1" wide paper tape using 7 or 8 bit ASCII code. Each byte of data to be stored is converted to two half bytes. The half bytes (whose possible values are 0 to F<sub>HEX</sub>) are translated into their ASCII equivalents and written onto paper tape in this form.

Each record output begins with a semicolon (";") character (ASCII 3B) to mark the start of a valid record. The next byte transmitted (Range: 1 to 18<sub>HEX</sub>) is the number of data bytes contained in the record. The record's starting address high (1 byte, 2 characters), starting address low (1 byte, 2 characters), and data (usually 24 bytes, 48 characters) follow. Each record is terminated by the record's check-sum (2 bytes, 4 characters), a carriage return (ASCII 0D), Line Feed (ASCII 0A), and six "NULL" characters (ASCII 0). No other characters, such as rubouts, are allowed anywhere.

The last record transmitted has zero data bytes (indicated by ;00). The starting address field is replaced by a four digit HEX number representing the total number of data records contained in the transmission, followed by the records usual check-sum digits. An "XOFF" character ends the transmission.

**EXAMPLE:**

```
;180000FFEEDCCBBAA0099887766554433221122334455667788990AFC;0000010001
```

All records must be punched in consecutive order and the data at each address must be completely and explicitly defined. All invalid data will be ignored and zeros substituted. Additional information as described in section entitled "TITLE CARDS" should be provided at transmission.

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## 6500 MICROPROCESSORS

### THE 6500 MICROPROCESSOR FAMILY CONCEPT —

The 6500 Series Microprocessors represent the first totally software compatible microprocessor family. This family of products includes a range of software compatible microprocessors which provide a selection of addressable memory range, interrupt input options and on-chip clock oscillators and drivers. All of the microprocessors in the 6500 group are software compatible within the group and are bus compatible with the M6800 product offering.

The family includes six microprocessors with on-board clock oscillators and drivers and four microprocessors driven by external clocks. The on-chip clock versions are aimed at high performance, low cost applications where single phase inputs, crystal or RC inputs provide the time base. The external clock versions are geared for the multi processor system applications where maximum timing control is mandatory. All versions of the microprocessors are available in 1 MHz, 2 MHz ("A" suffix on product numbers), and 3 MHz ("B" suffix on product numbers) maximum operating frequencies.

### FEATURES OF THE 6500 FAMILY

- Single +5 volt supply
- N channel, silicon gate, depletion load technology
- Eight bit parallel processing
- 56 Instructions
- Decimal and binary arithmetic
- Thirteen addressing modes
- True indexing capability
- Programmable stack pointer
- Variable length stack
- Interrupt capability
- Non-maskable interrupt
- Use with any type or speed memory
- 8 BIT Bi-directional Data Bus
- Addressable memory range of up to 65K bytes
- "Ready" input (for single cycle execution)
- Direct memory access capability
- Bus compatible with M6800
- Choice of external or on-board clocks
- 1 MHz, 2 MHz, and 3 MHz operation
- On-the-chip clock options
  - \* External single clock input
  - \* RC time base input
  - \* Crystal time base input
- Pipeline architecture

### MEMBERS OF THE 6500 MICROPROCESSOR (CPU) FAMILY

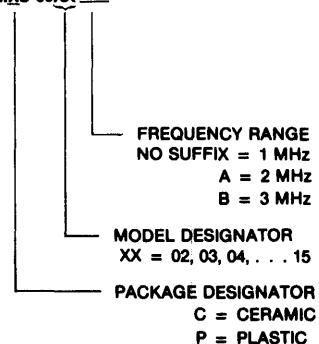
#### Microprocessors with On-Chip Clock Oscillator

Model	Addressable Memory
R6502	65K Bytes
R6503	4K Bytes
R6504	8K Bytes
R6505	4K Bytes
R6506	4K Bytes
R6507	8K Bytes

#### Microprocessors with External Two Phase Clock Inputs

Model	Addressable Memory
R6512	65K Bytes
R6513	4K Bytes
R6514	8K Bytes
R6515	4K Bytes

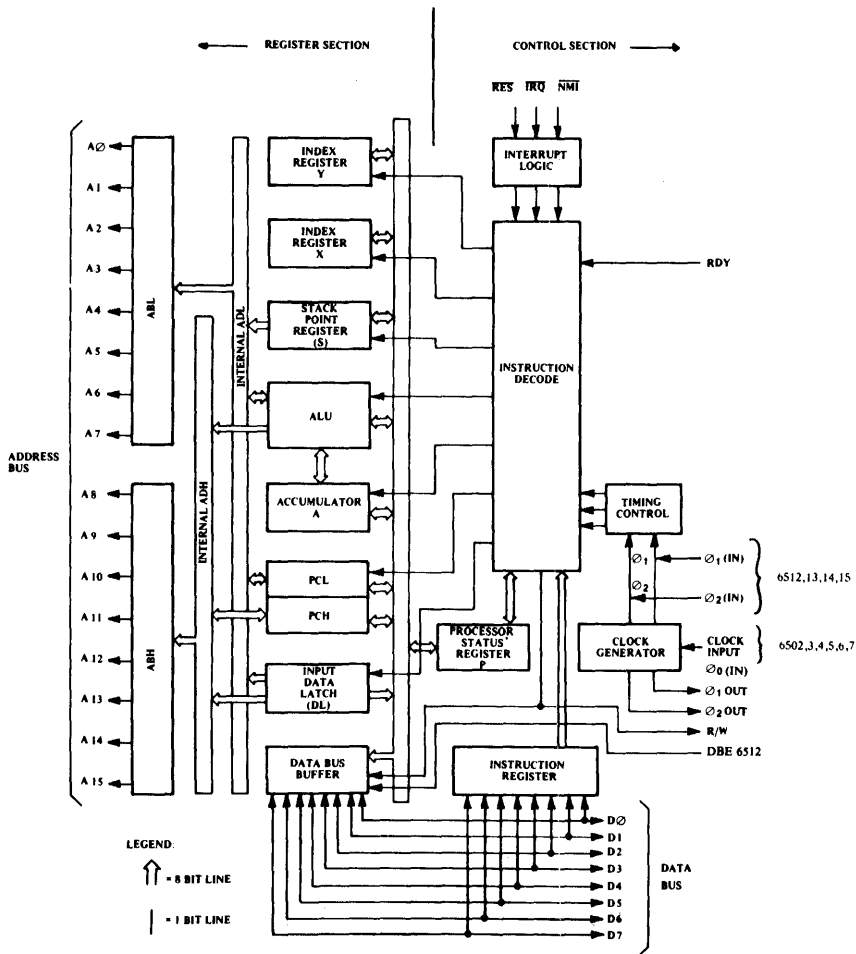
### ORDER NUMBER: MXS 65XX



**COMMENTS ON THE DATA SHEET**

The data sheet is constructed to review first the basic "Common Characteristics"—those features which are common to the general family of microprocessors. Subsequent to a review of the family characteristics will be sections devoted to each member of the group with specific features of each.

**COMMON CHARACTERISTICS**



Note: 1. Clock Generator is not included on 6512,13,14,15  
 2. Addressing Capability and control options vary with each of the 6500 Products.

**6500 Internal Architecture**

**COMMON CHARACTERISTICS**
**MAXIMUM RATINGS**

RATING	SYMBOL	VALUE	UNIT
SUPPLY VOLTAGE	V <sub>CC</sub>	-0.3 to +7.0	Vdc
INPUT VOLTAGE	V <sub>IN</sub>	-0.3 to +7.0	Vdc
OPERATING TEMPERATURE	T <sub>A</sub>	0 to +70	°C
STORAGE TEMPERATURE	T <sub>STG</sub>	-55 to +150	°C

This device contains input protection against damage due to high static voltages or electric fields; however, precautions should be taken to avoid application of voltages higher than the maximum rating.

**ELECTRICAL CHARACTERISTICS (V<sub>CC</sub> = 5.0V ± 5%, V<sub>SS</sub> = 0, T<sub>A</sub> = 0° to +70°C)**

∅<sub>1</sub>, ∅<sub>2</sub> (In) applies to 6512, 13, 14, 15; ∅<sub>0</sub> (In) applies to 6502, 03, 04, 05, 06 and 07

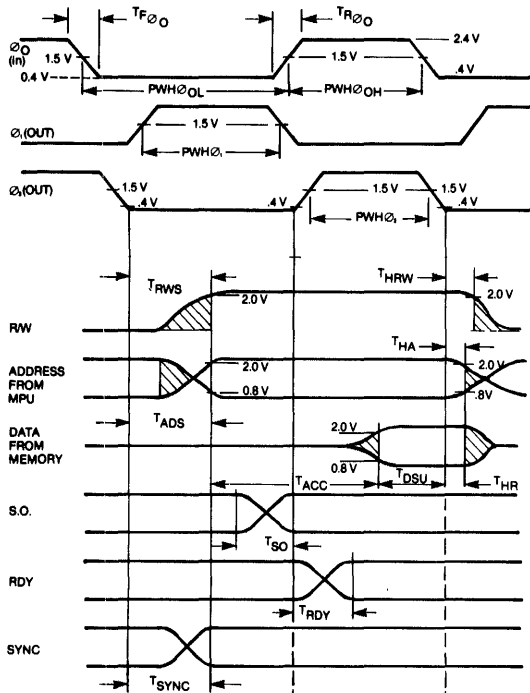
CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT
Input High Voltage Logic, ∅ <sub>0</sub> (In) ∅ <sub>1</sub> , ∅ <sub>2</sub> (In)	V <sub>IH</sub>	V <sub>SS</sub> + 2.4 V <sub>CC</sub> - 0.2	— —	V <sub>CC</sub> V <sub>CC</sub> + 1.0V	Vdc Vdc
Input High Voltage RES, NMI, RDY, IRQ, Data, S.O.		V <sub>SS</sub> + 2.0	—	—	Vdc
Input Low Voltage Logic, ∅ <sub>0</sub> (In) ∅ <sub>1</sub> , ∅ <sub>2</sub> (In)	V <sub>IL</sub>	V <sub>SS</sub> - 0.3 V <sub>SS</sub> - 0.3	— —	V <sub>SS</sub> + 0.4 V <sub>SS</sub> + 0.2	Vdc Vdc
Input Low Voltage RES, NMI, RDY, IRQ, Data, S.O.		—	—	V <sub>SS</sub> + 0.8	Vdc
Input Leakage Current (V <sub>IN</sub> = 0 to 5.25V, V <sub>CC</sub> = 5.25V) Logic (Excl. RDY, S.O.) ∅ <sub>1</sub> , ∅ <sub>2</sub> (In) ∅ <sub>0</sub> (In)	I <sub>IN</sub>	— — —	— — —	2.5 100 10.0	μA μA μA
Three State (Off State) Input Current (V <sub>IN</sub> = 0.4 to 2.4V, V <sub>CC</sub> = 5.25V) Data Lines	I <sub>TSI</sub>	—	—	10	μA
Output High Voltage (I <sub>OH</sub> = -100μAdc, V <sub>CC</sub> = 4.75V) SYNC, Data, AO-A15, RW	V <sub>OH</sub>	V <sub>SS</sub> + 2.4	—	—	Vdc
Out Low Voltage (I <sub>OL</sub> = 1.8mAdc, V <sub>CC</sub> = 4.75V) SYNC, Data, AO-A15, RW	V <sub>OL</sub>	—	—	V <sub>SS</sub> + 0.4	Vdc
Power Supply Current	I <sub>CC</sub>	—	70	160	mA
Capacitance (V <sub>IN</sub> = 0, T <sub>A</sub> = 25°C, f = 1MHz)	C				pF
Logic	C <sub>IN</sub>	—	—	10	
Data		—	—	15	
AO-A15, RW, SYNC	C <sub>OUT</sub>	—	—	12	
∅ <sub>0</sub> (In)	C∅ <sub>0</sub> (In)	—	—	15	
∅ <sub>1</sub>	C∅ <sub>1</sub>	—	30	50	
∅ <sub>2</sub>	C∅ <sub>2</sub>	—	50	80	

Note: IRQ and NMI require 3K pull-up resistors.

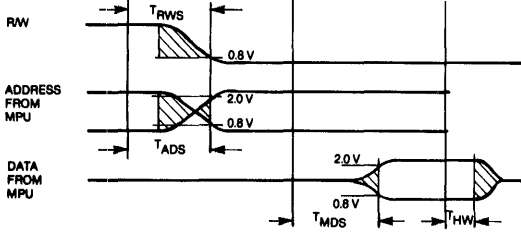
## COMMON CHARACTERISTICS

Clock Timing— 6502, 03, 04, 05, 06, 07

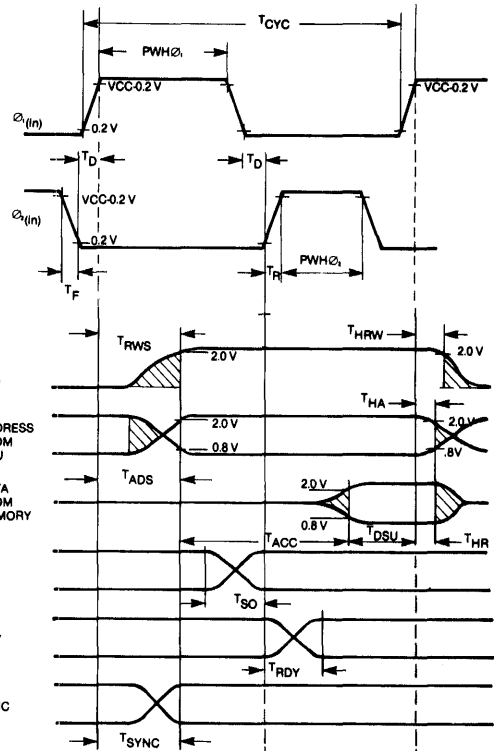
Clock Timing— 6512, 13, 14, 15



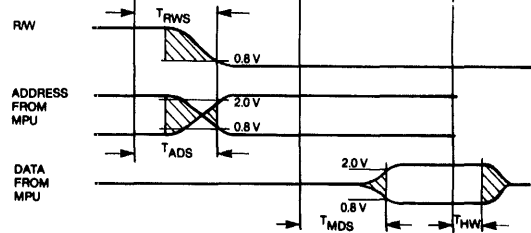
Timing for Reading Data from Memory or Peripherals



Timing for Writing Data to Memory or Peripherals



Timing for Reading Data from Memory or Peripherals



Timing for Writing Data to Memory or Peripherals

MOS TECHNOLOGIES



**COMMON CHARACTERISTICS**
**1 MHz TIMING**
**2 MHz TIMING**
**3 MHz TIMING**

Electrical Characteristics: ( $V_{CC} = 5V \pm 5\%$ ,  $V_{SS} = 0V$ ,  $T_A = 0^\circ-70^\circ C$ )  
 Minimum clock frequency = 50 KHz

**CLOCK TIMING—8502, 03, 04, 05, 06, 07**

CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	UNITS
Cycle Time	$T_{CYC}$	1000	—	—	500	—	—	333	—	—	ns
$\phi_{0(N)}$ Pulse Width (measured at 1.5v)	$PWH\phi_0$	480	—	520	240	—	260	160	—	170	ns
$\phi_0(N)$ Rise, Fall Time	$TR\phi_0, TF\phi_0$	—	—	10	—	—	10	—	—	10	ns
Delay Time between Clocks (measured at 1.5v)	$T_D$	5	—	—	5	—	—	5	—	—	ns
$\phi_{1(OUT)}$ Pulse Width (measured at 1.5v)	$PWH\phi_1$	$PWH\phi_{OL} - 20$	—	$PWH\phi_{OL}$	$PWH\phi_{OL} - 20$	—	$PWH\phi_{OL}$	$PWH\phi_{OL} - 20$	—	$PWH\phi_{OL}$	ns
$\phi_{2(OUT)}$ Pulse Width (measured at 1.5v)	$PWH\phi_2$	$PWH\phi_{OH} - 40$	—	$PWH\phi_{OH} - 10$	$PWH\phi_{OH} - 40$	—	$PWH\phi_{OH} - 10$	$PWH\phi_{OH} - 40$	—	$PWH\phi_{OH} - 10$	ns
$\phi_{1(OUT)} \phi_{2(OUT)}$ Rise, Fall Time (measured .8v to 2.0v) (Load $\frac{1}{2}$ 30pF $\frac{1}{2}$ 1 TTL)	$T_R, T_F$	—	—	25	—	—	25	—	—	25	ns

**CLOCK TIMING—8512, 13, 14, 15**

CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	UNITS
Cycle Time	$T_{CYC}$	1000	—	—	500	—	—	333	—	—	ns
Clock Pulse Width $\phi_1$ (Measured at $V_{CC} - 0.2v$ )	$PWH \phi_1$	430	—	—	215	—	—	150	—	—	ns
$\phi_2$	$PWH \phi_2$	470	—	—	235	—	—	180	—	—	ns
Fall Time, Rise Time (Measured from 0.2v to $V_{CC} - 0.2v$ )	$T_F, T_R$	—	—	25	—	—	15	—	—	15	ns
Delay Time between Clocks (Measured at 0.2v)	$T_D$	0	—	—	0	—	—	0	—	—	ns

**READWRITE TIMING (LOAD = 1TTL)**

CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	UNITS
Read/Write Setup Time from 8500	$T_{RWS}$	—	100	300	—	100	150	—	80	110	ns
Address Setup Time from 8500	$T_{ADS}$	—	100	300	—	100	150	—	80	125	ns
Memory Read Access Time	$T_{ACC}$	—	—	575	—	—	300	—	—	170	ns
Data Stability Time Period	$T_{DSU}$	100	—	—	50	—	—	50	—	—	ns
Data Hold Time—Read	$T_{HR}$	10	—	—	10	—	—	10	—	—	ns
Data Hold Time—Write	$T_{HW}$	30	80	—	30	80	—	10	—	—	ns
Data Setup Time from 8500	$T_{MDS}$	—	150	200	—	75	100	—	70	100	ns
S.O. Setup Time	$T_{SO}$	100	—	—	50	—	—	50	—	—	ns
SYNC Setup Time from 8500	$T_{SYNC}$	—	—	350	—	—	175	—	—	120	ns
Address Hold Time	$T_{HA}$	30	80	—	30	80	—	10	30	—	ns
R/W Hold Time	$T_{HRW}$	30	80	—	30	80	—	10	30	—	ns
RDY Setup Time	$T_{RDY}$	100	—	—	50	—	—	—	—	15	ns



**COMMON CHARACTERISTICS**
**6500 SIGNAL DESCRIPTION**
**Clocks ( $\phi_1, \phi_2$ )**

The 651X requires a two phase non-overlapping clock that runs at the Vcc voltage level. The 6500 clocks are supplied with an internal clock generator. The frequency of these clocks is externally controlled.

**Address Bus ( $A_7-A_0$ )**

These outputs are TTL compatible, capable of driving one standard TTL load and 130 pf.

**Data Bus ( $D_7-D_0$ )**

Eight pins are used for the data bus. This is a bi-directional bus, transferring data to and from the device and peripherals. The outputs are tri-state buffers capable of driving one standard TTL load and 130pf.

**Data Bus Enable (DBE)**

This TTL compatible input allows external control of the tri-state data output buffers and will enable the microprocessor bus driver when in the high state. In normal operation DBE would be driven by the phase two ( $\phi_2$ ) clock, thus allowing data output from microprocessor only during  $\phi_2$ . During the read cycle, the data bus drivers are internally disabled, becoming essentially an open circuit. To disable data bus drivers externally, DBE should be held low.

**Ready (RDY)**

This input signal allows the user to single cycle the microprocessor on all cycles except write cycles. A negative transition to the low state during or coincident with phase one ( $\phi_1$ ) and up to 100ns after phase two ( $\phi_2$ ) will halt the microprocessor with the output address lines reflecting the current address being fetched. This condition will remain through a subsequent phase two ( $\phi_2$ ) in which the Ready signal is low. This feature allows microprocessor interfacing with low speed PROMS as well as fast (max. 2 cycle) Direct Memory Access (DMA). If Ready is low during a write cycle, it is ignored until the following read operation.

**Interrupt Request ( $\overline{IRQ}$ )**

This TTL level input requests that an interrupt sequence begin within the microprocessor. The microprocessor will complete the current instruction being executed before recognizing the request. At that time, the interrupt mask bit in the Status Code Register will be examined. If the interrupt mask flag is not set, the microprocessor will begin an interrupt sequence. The Program Counter and Processor Status Register are stored in the stack. The microprocessor will then set the interrupt mask flag high so that no further interrupts may occur. At the end of this cycle, the program counter low will be loaded from address FFFE, and program counter high from location FFFF, therefore transferring program control to the memory vector located at these addresses. The RDY signal must be in the high state for any interrupt to be recognized. A 3K $\Omega$  external resistor should be used for proper wire-OR operation.

**Non-Maskable Interrupt ( $\overline{NMI}$ )**

A negative going edge on this input requests that a non-maskable interrupt sequence be generated within the microprocessor. NMI is an unconditional interrupt. Following completion of the current instruction, the sequence of operations defined for  $\overline{IRQ}$  will be performed, regardless of the interrupt mask flag status. The vector address loaded into the program counter, low and high, are locations FFFA and FFFB respectively, thereby transferring program control to the memory vector located at these addresses. The instructions loaded at these locations cause the microprocessor to branch to a non-maskable interrupt routine in memory.

NMI also requires an external 3K $\Omega$  resistor to Vcc for proper wire-OR operations.

Inputs  $\overline{IRQ}$  and  $\overline{NMI}$  are hardware interrupt lines that are sampled during  $\phi_2$  (phase 2) and will begin the appropriate interrupt routine on the  $\phi_1$  (phase 1) following the completion of the current instruction.

**Set Overflow Flag (S.O.)**

A NEGATIVE going edge on this input sets the overflow bit in the Status Code Register. This signal is sampled on the trailing edge of  $\phi_1$ .

**SYNC**

This output line is provided to identify those cycles in which the microprocessor is doing an OP CODE fetch. The SYNC line goes high during  $\phi_1$  of an OP CODE fetch and stays high for the remainder of that cycle. If the RDY line is pulled low during the  $\phi_1$  clock pulse in which SYNC went high, the processor will stop in its current state and will remain in the state until the RDY line goes high. In this manner, the SYNC signal can be used to control RDY to cause single instruction execution.

**Reset**

This input is used to reset or start the microprocessor from a power down condition. During the time that this line is held low, writing to or from the microprocessor is inhibited. When a positive edge is detected on the input, the microprocessor will immediately begin the reset sequence.

After a system initialization time of six clock cycles, the mask interrupt flag will be set and the microprocessor will load the program counter from the memory vector locations FFFC and FFFD. This is the start location for program control.

After Vcc reaches 4.75 volts in a power up routine, reset must be held low for at least two clock cycles. At this time the R/W and (SYNC) signal will become valid.

When the reset signal goes high following these two clock cycles, the microprocessor will proceed with the normal reset procedure detailed above.

**COMMON CHARACTERISTICS**
**ADDRESSING MODES**

**ACCUMULATOR ADDRESSING**—This form of addressing is represented with a one byte instruction, implying an operation on the accumulator.

**IMMEDIATE ADDRESSING**—In immediate addressing, the operand is contained in the second byte of the instruction, with no further memory addressing required.

**ABSOLUTE ADDRESSING**—In absolute addressing, the second byte of the instruction specifies the eight low order bits of the effective address while the third byte specifies the eight high order bits. Thus, the absolute addressing mode allows access to the entire 65K bytes of addressable memory.

**ZERO PAGE ADDRESSING**—The zero page instructions allow for shorter code and execution times by only fetching the second byte of the instruction and assuming a zero high address byte. Careful use of the zero page can result in significant increase in code efficiency.

**INDEXED ZERO PAGE ADDRESSING**—(X, Y indexing)—This form of addressing is used in conjunction with the index register and is referred to as "Zero Page, X" or "Zero Page, Y." The effective address is calculated by adding the second byte to the contents of the index register. Since this is a form of "Zero Page" addressing, the content of the second byte references a location in page zero. Additionally, due to the "Zero Page" addressing nature of this mode, no carry is added to the high order 8 bits of memory and crossing of page boundaries does not occur.

**INDEXED ABSOLUTE ADDRESSING**—(X, Y indexing)—This form of addressing is used in conjunction with X and Y Index register and is referred to as "Absolute, X," and "Absolute, Y." The effective address is formed by adding the contents of X and Y to the address contained in the second and third bytes of the instruction. This mode allows the index register to contain the index or count value and the instruction to contain the base address. This type of indexing allows any location referencing and the index to modify multiple fields resulting in reduced coding and execution time.

**IMPLIED ADDRESSING**—In the implied addressing mode, the address containing the operand is implicitly stated in the operation code of the instruction.

**RELATIVE ADDRESSING**—Relative addressing is used only with branch instructions and establishes a destination for the conditional branch.

The second byte of the instruction becomes the operand which is an "Offset" added to the contents of the lower eight bits of the program counter when the counter is set at the next instruction. The range of the offset is -128 to +127 bytes from the next instruction.

**INDEXED INDIRECT ADDRESSING**—In indexed indirect addressing (referred to as (Indirect, X)), the second byte of the instruction is added to the contents of the X index register, discarding the carry. The result of this addition points to a memory location on page zero whose contents is the low order eight bits of the effective address. The next memory location in page zero contains the high order eight bits of the effective address. Both memory locations specifying the high and low order bytes of the effective address must be in page zero.

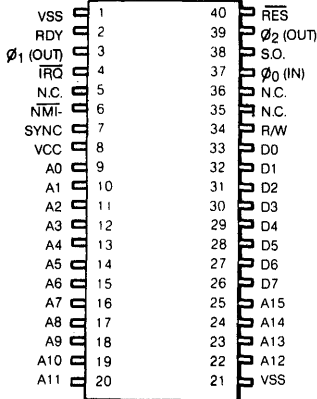
**INDIRECT INDEXED ADDRESSING**—In indirect indexed addressing (referred to as (Indirect), Y), the second byte of the instruction points to a memory location in page zero. The contents of this memory location is added to the contents of the Y index register, the result being the low order eight bits of the effective address. The carry from this addition is added to the contents of the next page zero memory location, the result being the high order eight bits of the effective address.

**ABSOLUTE INDIRECT**—The second byte of the instruction contains the low order eight bits of a memory location. The high order eight bits of that memory location is contained in the third byte of the instruction. The contents of the fully specified memory location is the low order byte of the effective address. The next memory location contains the high order byte of the effective address which is loaded into the sixteen bits of the program counter.

**INSTRUCTION SET—ALPHABETIC SEQUENCE**

ADC	Add Memory to Accumulator with Carry	LDA	Load Accumulator with Memory
AND	"AND" Memory with Accumulator	LDX	Load Index X with Memory
ASL	Shift Left One Bit (Memory or Accumulator)	LDY	Load Index Y with Memory
BCC	Branch on Carry Clear	LSR	Shift One Bit Right (Memory or Accumulator)
BCS	Branch on Carry Set	NOP	No Operation
BEQ	Branch on Result Zero	ORA	"OR" Memory with Accumulator
BIT	Test Bits in Memory with Accumulator	PHA	Push Accumulator on Stack
BMI	Branch on Result Minus	PHP	Push Processor Status on Stack
BNE	Branch on Result not Zero	PLA	Pull Accumulator from Stack
BPL	Branch on Result Plus	PLP	Pull Processor Status from Stack
BRK	Force Break	ROL	Rotate One Bit Left (Memory or Accumulator)
BVC	Branch on Overflow Clear	ROR	Rotate One Bit Right (Memory or Accumulator)
BVS	Branch on Overflow Set	RTI	Return from Interrupt
CLC	Clear Carry Flag	RTS	Return from Subroutine
CLD	Clear Decimal Mode	SBC	Subtract Carry from Accumulator with Borrow
CLI	Clear Interrupt Disable Bit	SEC	Set Carry Flag
CLV	Clear Overflow Flag	SED	Set Decimal Mode
CMP	Compare Memory and Accumulator	SEI	Set Interrupt Disable Status
CPX	Compare Memory and Index X	STA	Store Accumulator in Memory
CPY	Compare Memory and Index Y	STX	Store Index X in Memory
DEC	Decrement Memory by One	STY	Store Index Y in Memory
DEX	Decrement Index X by One	TAX	Transfer Accumulator to Index X
DEY	Decrement Index Y by One	TAY	Transfer Accumulator to Index Y
EOR	"Exclusive-or" Memory with Accumulator	TSX	Transfer Stack Pointer to Index X
INC	Increment Memory by One	TXA	Transfer Index X to Accumulator
INX	Increment Index X by One	TXS	Transfer Index X to Stack Register
INY	Increment Index Y by One	TYA	Transfer Index Y to Accumulator
JMP	Jump to New Location		
JSR	Jump to New Location Saving Return Address		

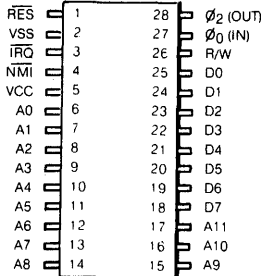
MICRO-COMPUTERS



### 6502—40 Pin Package

#### Features of 6502

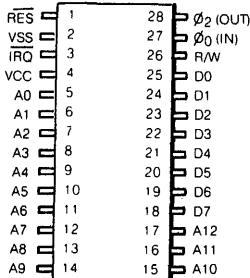
- 65K Addressable Bytes of Memory (A0-A15)
- $\overline{\text{IRQ}}$  Interrupt
- On-the-chip Clock
  - TTL Level Single Phase Input
  - RC Time Base Input
  - Crystal Time Base Input
- SYNC Signal (can be used for single instruction execution)
- RDY Signal (can be used to halt or single cycle execution)
- Two Phase Output Clock for Timing of Support Chips
- NMI Interrupt



### 6503—28 Pin Package

#### Features of 6503

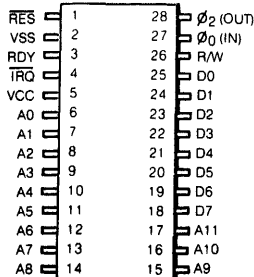
- 4K Addressable Bytes of Memory (A0-A11)
- On-the-chip Clock
- $\overline{\text{IRQ}}$  Interrupt
- NMI Interrupt
- 8 Bit Bidirectional Data Bus



### 6504—28 Pin Package

#### Features of 6504

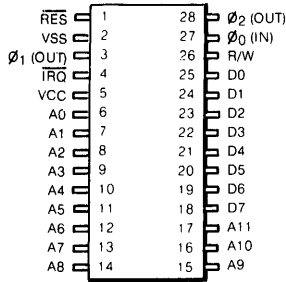
- 8K Addressable Bytes of Memory (A0-A12)
- On-the-chip Clock
- $\overline{\text{IRQ}}$  Interrupt
- 8 Bit Bidirectional Data Bus



### 6505—28 Pin Package

#### Features of 6505

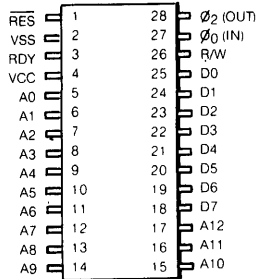
- 4K Addressable Bytes of Memory (A0-A11)
- On-the-chip Clock
- $\overline{\text{IRQ}}$  Interrupt
- RDY Signal
- 8 Bit Bidirectional Data Bus



### 6506—28 Pin Package

#### Features of 6506

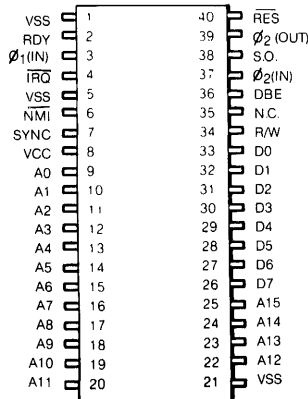
- 4K Addressable Bytes of Memory (A0-A11)
- On-the-chip Clock
- $\overline{\text{IRQ}}$  Interrupt
- Two phase output clock for timing of support chips
- 8 Bit Bidirectional Data Bus



### 6507—28 Pin Package

#### Features of 6507

- 8K Addressable Bytes of Memory (A0-A12)
- On-the-chip Clock
- RDY Signal
- 8 Bit Bidirectional Data Bus

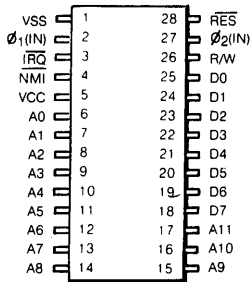


### 6512—40 Pin Package

#### Features of 6512

- 65K Addressable Bytes of Memory (A0-A15)
- $\overline{\text{IRQ}}$  Interrupt
- $\overline{\text{NMI}}$  Interrupt
- RDY Signal
- 8 Bit Bidirectional Data Bus
- SYNC Signal
- Two phase clock input
- Data Bus Enable

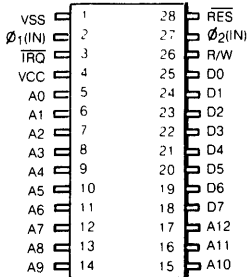
M.S.C. 0000000000



**6513—28 Pin Package**

**Features of 6513**

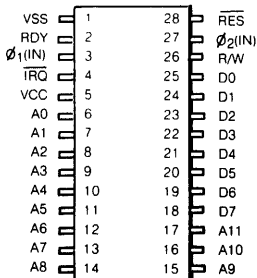
- 4K Addressable Bytes of Memory (A0-A11)
- Two phase clock input
- $\overline{\text{IRQ}}$  Interrupt
- NMI Interrupt
- 8 Bit Bidirectional Data Bus



**6514—28 Pin Package**

**Features of 6514**

- 8K Addressable Bytes of Memory (A0-A12)
- Two phase clock input
- $\overline{\text{IRQ}}$  Interrupt
- 8 Bit Bidirectional Data Bus



**6515—28 Pin Package**

**Features of 6515**

- 4K Addressable Bytes of Memory (A0-A11)
- Two phase clock input
- $\overline{\text{IRQ}}$  Interrupt
- RDY Signal
- 8 Bit Bidirectional Data Bus

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